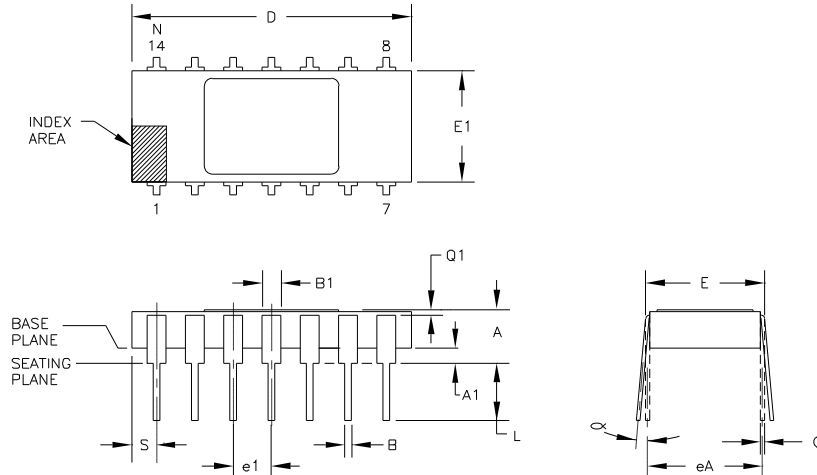


Package Number 169 - 14-Lead, Ceramic Side Braze DIP, .300 Wide



| DIM | INCHES | | MILLIMETERS | | NOTE |
|-----|-----------|------|-------------|-------|------|
| | MIN. | MAX. | MIN. | MAX. | |
| A | .105 | .175 | 2.67 | 4.45 | |
| A1 | .025 | .055 | 0.64 | 1.40 | |
| B | .015 | .021 | 0.38 | 0.53 | 5 |
| B1 | .038 | .060 | 0.97 | 1.52 | 5 |
| C | .008 | .012 | 0.20 | 0.30 | |
| D | .690 | .770 | 17.53 | 19.56 | |
| E | .290 | .325 | 7.37 | 8.26 | |
| E1 | .280 | .310 | 7.11 | 7.87 | 6 |
| e1 | .100 TYP. | | 2.54 TYP. | | 2 |
| eA | .300 TYP. | | 7.62 TYP. | | 2 |
| L | .125 | .175 | 3.18 | 4.45 | |
| N | 14 | | 14 | | 4 |
| Q1 | .010 | -- | 0.25 | -- | |
| S | .030 | .095 | 0.76 | 2.41 | |

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1973.
 2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
 3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
 4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE ($A1 = 0$), TERMINALS LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ169 REV.: F
 JEDEC NUMBER: MO-36-AB

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